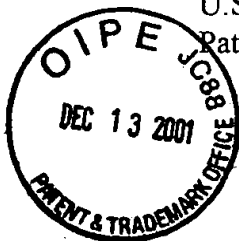


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BY APPLICANT

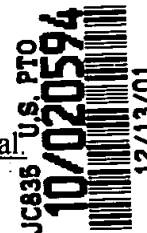
(Use several sheets if necessary)

Atty Docket No.: 70408

Ser. No.:

Applicant: SCHREDL et al.

Filing Date:

Group: 1772

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OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

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U	<u>Roland Heitmann</u>	<u>1995</u>	<u>Die elementaren Verbindungen: BGA und Flip-Chip</u>	<u>Productronic 7</u>	<u>No</u>
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[Signature]

~~SAVAGE, J.~~ L. Tran
Examiner

1/21/03

Date Considered